ABSTRACT

The present invention provides a connecting device for connection to a body of semiconductor material. The body of semiconductor material includes an integrated circuit that contains a plurality of clusters of signal transmissive connector elements arranged in a predetermined disposition. The connecting device includes a plurality of groups of signal transmissive connector members for connection to an associated cluster of signal transmissive connector elements. The disposition of the signal transmissive connector members in each group matches the disposition of the signal transmissive connector elements in that group's associated cluster. The connecting device further includes flexible portions between its respective groups of signal transmissive connector members. The flexible portions have a flexibility that allows the groups of signal transmissive connector members to move in relation to each other when they are connected to respective clusters of signal transmissive connector elements on the surface of a body of semiconductor material. As such, each group of signal transmissive connector members is able to maintain a secure and undamaged connection with a respective cluster of signal transmissive connector elements as the body of semiconductor material expands and contracts under thermal effects.